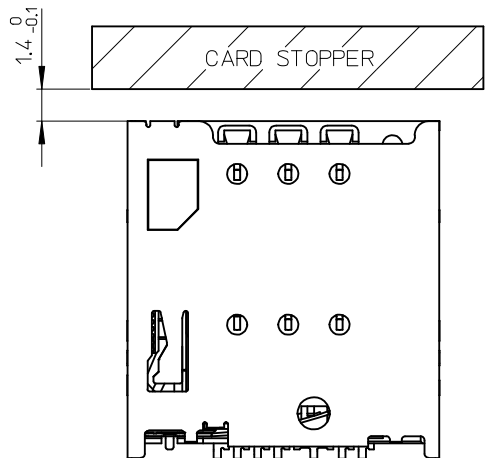


番号 NO.	名称 NAME	材料 MATERIAL	仕上げ(めっき) FINISHES (PLATING)
①	ハウジング HOUSING	液晶ポリマー(LCP)、ガラス充填、UL94 V-0、黒 LIQUID CRYSTAL POLYMER (LCP), GLASS FILLED, UL94 V-0, BLACK	
②	スライダー SLIDER	ステンレス鋼 STAINLESS STEEL	
③	ターミナル TERMINAL	焼青銅 PHOSPHOR BRONZE	接触部: 金めっき(0.5μmMIN.) 基板実装部: 金めっき 下地: ニッケルめっき(1.0μmMIN.) CONTACT AREA: GOLD PLATING (0.5 MICROMETER MINIMUM) SOLDER TAIL AREA: GOLD PLATING UNDERPLATE: NICKEL OVERALL (1.0 MICROMETER MINIMUM)
④	シェル SHELL	銅合金 COPPER ALLOY	
⑤	スプリング SPRING	ピアノ線 SWP	全面: ニッケルめっき NICKEL OVERALL
⑥	ピン PIN	ステンレス鋼 STAINLESS STEEL	
⑦	ディテクト レバー DETECT LEVER	焼青銅 PHOSPHOR BRONZE	接触部: 金めっき(0.2μmMIN.) 基板実装部: 金めっき 下地: ニッケルめっき(1.0μmMIN.) CONTACT AREA: GOLD PLATING (0.2 MICROMETER MINIMUM) SOLDER TAIL AREA: GOLD PLATING UNDERPLATE: NICKEL OVERALL (1.0 MICROMETER MINIMUM)
⑧	ディテクト スイッチ DETECT SWITCH	焼青銅 PHOSPHOR BRONZE	接触部: 金めっき(0.2μmMIN.) 基板実装部: 金めっき 下地: ニッケルめっき(1.0μmMIN.) CONTACT AREA: GOLD PLATING (0.2 MICROMETER MINIMUM) SOLDER TAIL AREA: GOLD PLATING UNDERPLATE: NICKEL OVERALL (1.0 MICROMETER MINIMUM)

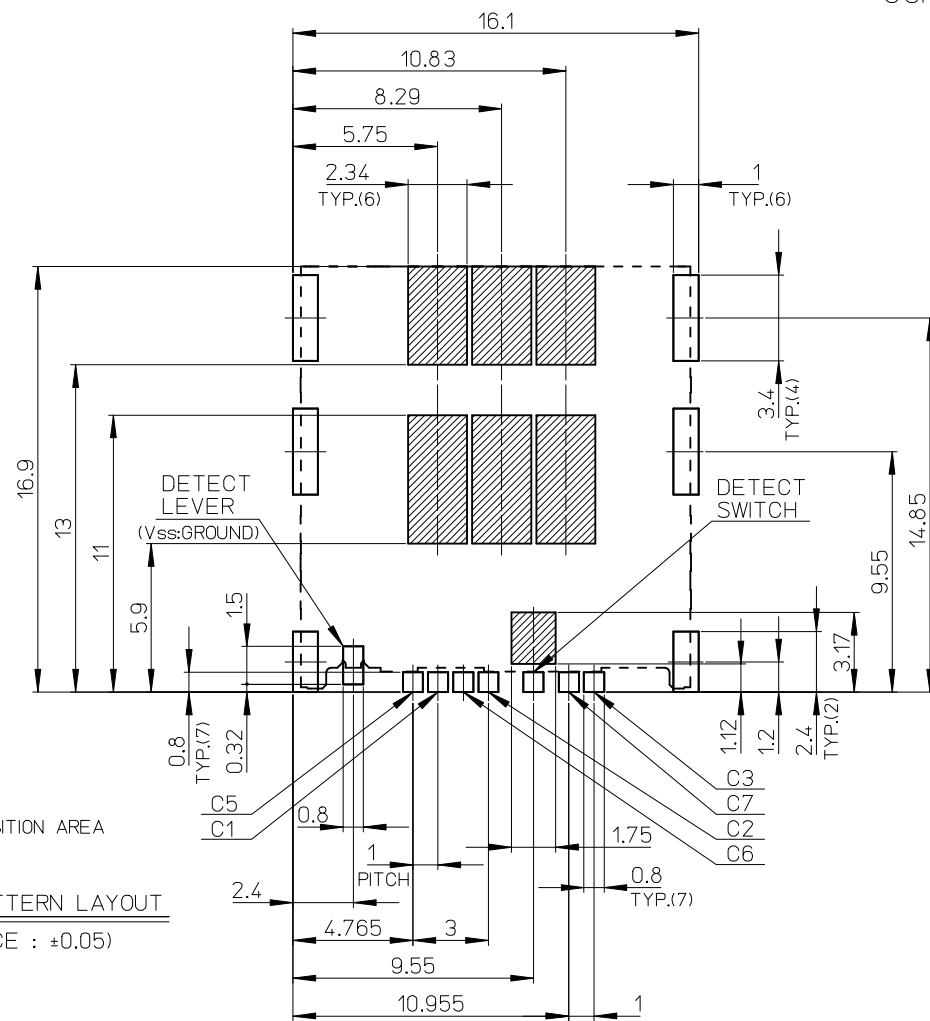
- NOTES**
- ターミナル及びびネイルの平坦度は 0.08 MAX.
(測定用定板面を基準)
TERMINAL AND NAIL COPLANARITY TO BE 0.08 MAX.(FROM GAUGE PLANE)
 - △ スタンドオフ寸法
STAND OFF DIMENSION
本寸法はコネクタ全高に含まれます。
STAND OFF DIMENSION IS INCLUDED IN THE CONNECTOR TOTAL HEIGHT.
 - パターン禁止エリア PATTERN PROHIBITION AREA
 - カード検知スイッチ DETECT SWITCH
- | | |
|--------------------------------|------------|
| カード挿入時 CARD INSERTING POSITION | オープン OPEN |
| カード未挿入時 NO CARD | クローズ CLOSE |
- 肉抜き位置は任意とする。CAVITY IS TO BE OPTIONAL.
 - ロット印字は任意とする。LOT NUMBERING IS TO BE OPTIONAL.
 - ELV及びRoHS 適合品 ELV AND RoHS COMPLIANT.
 - 括弧寸法は、参考値となります。(Dimension) : REFERENCE VALUE

503960-0694	6
EMBOSSED PACKAGE	極数
オーダー番号 ORDER NO.	CIRCUITS
CONNECTOR SERIES No. 503960-****	

RELEASED EC NO: J2013-0351 DRWN: MTAKASAKI 2012/09/10 CHKD: MTOMITA 2012/09/10 APPR: YO ITO 2012/09/20	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE	SCALE	DESIGN UNITS	THIRD ANGLE PROJECTION
			MM ONLY	1:1	METRIC	◎ □
	10 UNDER	±0.2	DRAWN BY	DATE	TITLE	
	10 OVER 30 UNDER	±0.25	MTAKASAKI	2012/09/10	MICRO SIM CARD CONN. PUSH/PUSH NORMAL TYPE ASS'Y	
30 OVER	±0.3	CHECKED BY	DATE	MATERIAL NO.		SHEET NO.
		MTOMITA	2012/09/10	SEE CHART		1 OF 2
		APPROVED BY	DATE	DOCUMENT NO.		
		YO ITO	2012/09/20	SD-503960-005		
		ANGULAR	±1 °	THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION		
		DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS				



RECOMMENDED CARD STOPPER POSITION



パターン禁止エリア
PATTERN PROHIBITION AREA

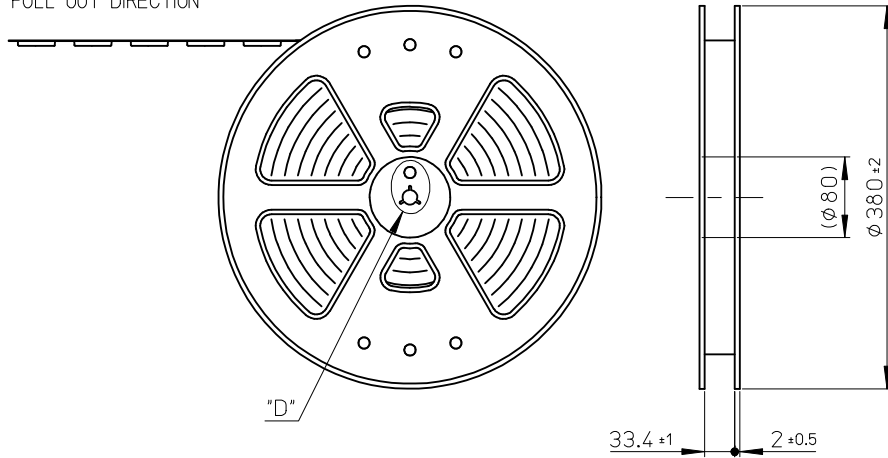
RECOMMENDED PCB PATTERN LAYOUT
(GENERAL TOLERANCE : ±0.05)

SEE SHEET 1 OF 2 EC NO: J2013-0351 DRWN: MTAKASAKI 2012/09/10 CHKD: MTOMITA 2012/09/10 APPR: YOITO 2012/09/20	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE 1:1	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION
	10 UNDER	±0.2	DRAWN BY MTAKASAKI	DATE 2012/09/10	TITLE MICRO SIM CARD CONN. PUSH/PUSH NORMAL TYPE ASS'Y		
	10 OVER 30 UNDER	±0.25	CHECKED BY MTOMITA	DATE 2012/09/10			
	30 OVER	±0.3	APPROVED BY YOITO	DATE 2012/09/20	molex MATERIAL NO. SEE SHEET 1 OF 2 DOCUMENT NO. SD-503960-005 SHEET NO. 2 OF 2		
ANGULAR ±1 °		SIZE A3		THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION			
DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS							

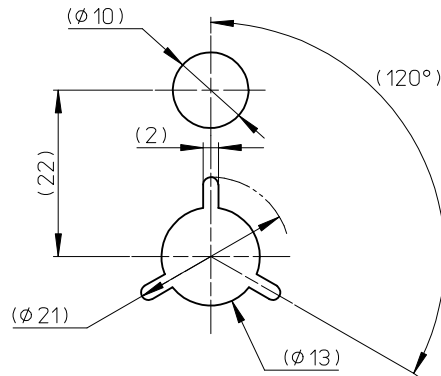
NOTES

- 製品詳細寸法については、SD 図面を参照下さい。
RE DETAILED DIMENSION, SEE SALES DRAWING.
- 梱包数量：1600 個／リール
NUMBER OF CONNECTORS：1600 PCS/REEL.
- リードテープ長さ LEAD TAPE LENGTH.

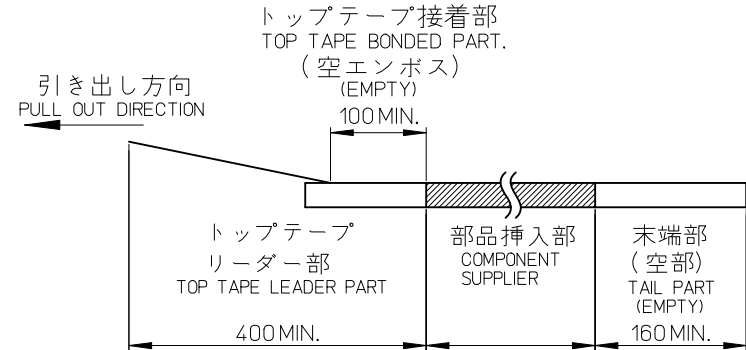
引き出し方向
PULL OUT DIRECTION



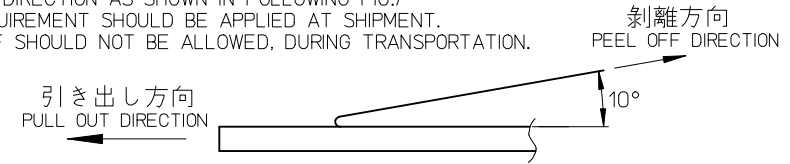
"D"



DETAIL "D"



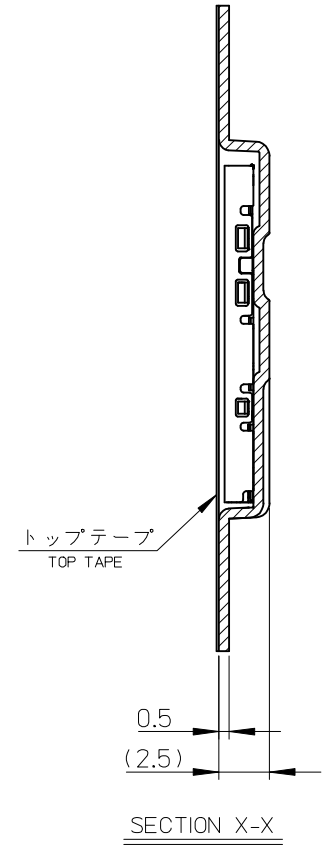
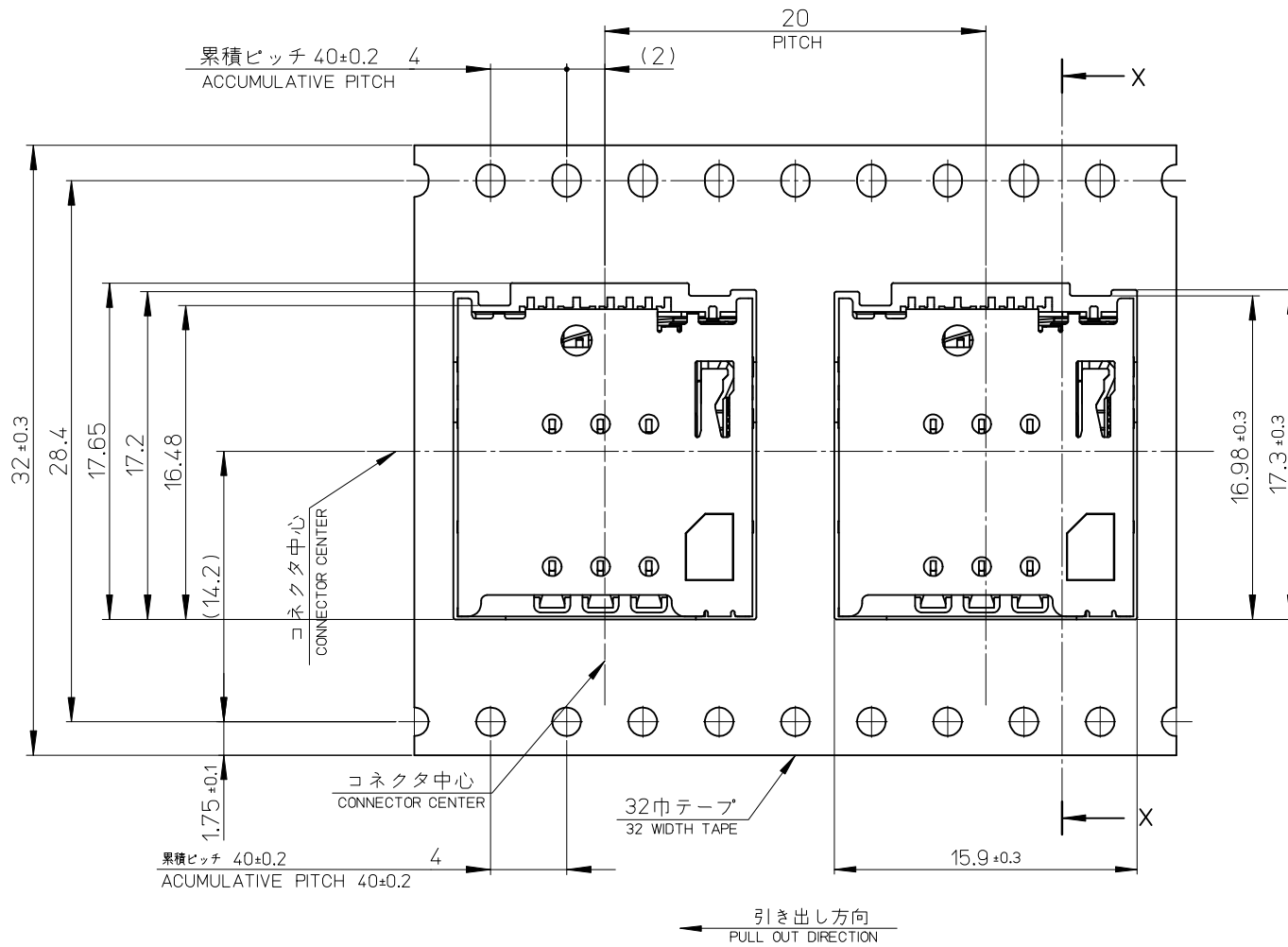
- トップテープの剥離強度：JIS C0806-3に準拠(剥離方向は下図参照)尚、本規格値は出荷時に適用。(但し、輸送時に剥離が発生しないこと。)
PEELING OFF FORCE OF TOP TAPE：BASED UPON JIS C0806-3 (PEELING DIRECTION AS SHOWN IN FOLLOWING FIG.) THIS REQUIREMENT SHOULD BE APPLIED AT SHIPMENT. PEEL OFF SHOULD NOT BE ALLOWED, DURING TRANSPORTATION.



- 材料 MATERIAL
キャリアテープ (CARRIER TAPE)：ポリスチレン (POLYSTYRENE)
トップテープ (TOP TAPE)：PET, PE, PEF
リール (REEL)：ポリスチレン (PS) <リサイクル材含む>
POLYSTYRENE (PS) <RECYCLE MATERIAL CONTAINED>

503960-0694	6
EMBOSSED PACKAGE	極数
オーダー番号 ORDER NO.	CIRCUITS
CONNECTOR SERIES No. 503960-****	

RELEASED EC NO.: J2013-0351 DRWN: MTAKASAKI 2012/09/10 CHKD: MTOMITA 2012/09/10 APPR: YOITO 2012/09/20 REV: A	DESCRIPTION GENERAL TOLERANCES (UNLESS SPECIFIED) 10 UNDER ±0.2 10 OVER 30 UNDER ±0.25 30 OVER ±0.3 ANGULAR ±1 ° DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS	DIMENSION STYLE MM ONLY DRAWN BY: MTAKASAKI CHECKED BY: MTOMITA APPROVED BY: YOITO MATERIAL NO. SEE CHART SIZE A3	SCALE 1:1 DESIGN UNITS METRIC THIRD ANGLE PROJECTION	TITLE
				MICRO SIM CARD CONN. PUSH/PUSH NORMAL TYPE EMBOSSED TAPE PACKAGE
				molex
				DOCUMENT NO. SD-503960-006 SHEET NO. 1 OF 2



SEE SHEET 1 OF 2 EC NO: J2013-0351 DRWN: MTAKASAKI 2012/09/10 CHKD: MTOMITA 2012/09/10 APPR: YOITO 2012/09/20	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY	SCALE 1:1	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION
	10 UNDER	± 0.2	DRAWN BY MTAKASAKI	DATE 2012/09/10	TITLE MICRO SIM CARD CONN. PUSH/PUSH NORMAL TYPE EMBOSSD TAPE PACKAGE	
	10 OVER 30 UNDER	± 0.25	CHECKED BY MTOMITA	DATE 2012/09/10	molex DOCUMENT NO. SD-503960-006 SHEET NO. 2 OF 2	
	30 OVER	± 0.3	APPROVED BY YOITO	DATE 2012/09/20		
ANGULAR ±1 °	DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS	MATERIAL NO. SEE SHEET 1 OF 2	THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION			